TECHNOPARTNER

S730

Silicone Potting Compound

REACH Compliant | RoHS Compliant

Features

- Good thermal conductivity
- Heat curing
- A:B = 1:1; Easy to mix
- Can be applied with pistol & Easy to assemble
- Low viscosity

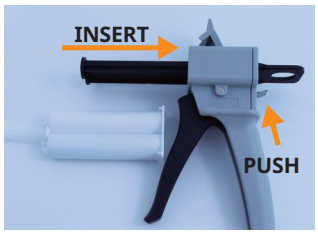
Applications

Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board,Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

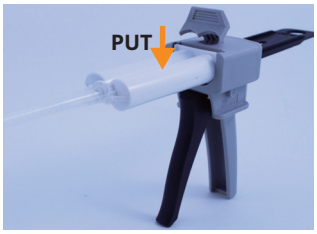
Storage

Epoxy Potting Compound has a shelf-life of twelve (12) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened contained at or below 25° C.

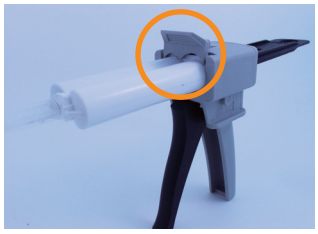
Operation Manual



① Push the latch and insert the stick.



② Put the tube in.


③ Close the cover.

Properties

Thermal Conductivity : 2.1 W/mK

0 0.8 1.2 1.4 1.6 1.7 1.8 2.2 3.2 3.6 4.0 4.5 5.0 15 20

Hardness : 17 (Shore A)

0 5 10 15 20 25 30 40 80

Properties	S730	Unit	Tolerance	Test Method
Thermal Conductivity	2.1	W/mK	±10%	ASTM D5470
Color	Gray	-	-	Visual
Dielectric Breakdown Voltage	12.2	KV/mm	±10%	ASTM D149
Volume Resistance	$>10^{13}$	Ohm-m	-	ASTM D257
Density	2.5	g/cm^3	±10%	ASTM D792
Working Temperature	-50~+200	° C	-	-
Viscosity	<50000	cps	-	ASTM D2393
Curing Time @25° C	300	Min	-	-
Curing Time @60° C	30	Min	-	-
Curing Time @100° C	5	Min	-	-
Standard Format	100g/1kg	Tube/Pot	-	-
Hardness	17	Shore A	±2	ASTM D2240
Mixing Ratio	1:1	gram	-	-

▶ Component A is a mixed material of epoxy and thermal conductive powder. It is normal to cause precipitation and stratification due to different density. Before use, please use a flat spatula or other stainless tools to evenly mix component A to achieve the best thermal conductivity.